



PCA9545A/45B/45C

4-channel I²C-bus switch with interrupt logic and reset

Rev. 8 — 14 May 2013

Product data sheet

1. General description

The PCA9545A/45B/45C is a quad bidirectional translating switch controlled via the I²C-bus. The SCL/SDA upstream pair fans out to four downstream pairs, or channels. Any individual SCx/SDx channel or combination of channels can be selected, determined by the contents of the programmable control register. Four interrupt inputs, INT0 to INT3, one for each of the downstream pairs, are provided. One interrupt output, $\overline{\text{INT}}$, acts as an AND of the four interrupt inputs.

An active LOW reset input allows the PCA9545A/45B/45C to recover from a situation where one of the downstream I²C-buses is stuck in a LOW state. Pulling the RESET pin LOW resets the I²C-bus state machine and causes all the channels to be deselected as does the internal power-on reset function.

The pass gates of the switches are constructed such that the V_{DD} pin can be used to limit the maximum high voltage which will be passed by the PCA9545A/45B/45C. This allows the use of different bus voltages on each pair, so that 1.8 V or 2.5 V or 3.3 V parts can communicate with 5 V parts without any additional protection. External pull-up resistors pull the bus up to the desired voltage level for each channel. All I/O pins are 5 V tolerant.

The PCA9545A, PCA9545B and PCA9545C are identical except for the fixed portion of the slave address.

2. Features and benefits

- 1-of-4 bidirectional translating switches
- I²C-bus interface logic; compatible with SMBus standards
- 4 active LOW interrupt inputs
- Active LOW interrupt output
- Active LOW reset input
- 2 address pins allowing up to 4 devices on the I²C-bus
- Alternate address versions A, B and C allow up to a total of 12 devices on the bus for larger systems or to resolve address conflicts
- Channel selection via I²C-bus, in any combination
- Power-up with all switch channels deselected
- Low R_{on} switches
- Allows voltage level translation between 1.8 V, 2.5 V, 3.3 V and 5 V buses
- No glitch on power-up
- Supports hot insertion
- Low standby current
- Operating power supply voltage range of 2.3 V to 5.5 V



- 5 V tolerant Inputs
- 0 Hz to 400 kHz clock frequency
- ESD protection exceeds 2000 V HBM per JESD22-A114 and 1000 V CDM per JESD22-C101
- Latch-up protection exceeds 100 mA per JESD78
- Three packages offered: SO20, TSSOP20, and HVQFN20

3. Ordering information

Table 1. Ordering information

| Type number | Topside marking | Package | | |
|-------------|-----------------|---------|--|----------|
| | | Name | Description | Version |
| PCA9545ABS | 9545A | HVQFN20 | plastic thermal enhanced very thin quad flat package; no leads; 20 terminals; body 5 × 5 × 0.85 mm | SOT662-1 |
| PCA9545AD | PCA9545AD | SO20 | plastic small outline package; 20 leads; body width 7.5 mm | SOT163-1 |
| PCA9545APW | PA9545A | TSSOP20 | plastic thin shrink small outline package; 20 leads; body width 4.4 mm | SOT360-1 |
| PCA9545BPW | PA9545B | | | |
| PCA9545CPW | PA9545C | | | |

3.1 Ordering options

Table 2. Ordering options

| Type number | Orderable part number | Package | Packing method | Minimum order quantity | Temperature range |
|-------------|-----------------------|---------|---|------------------------|-------------------------------------|
| PCA9545ABS | PCA9545ABS,118 | HVQFN20 | Reel 13" Q1/T1 *standard mark SMD | 6000 | T _{amb} = -40 °C to +85 °C |
| PCA9545AD | PCA9545AD,112 | SO20 | Standard marking * IC's tube - DSC bulk pack | 1520 | T _{amb} = -40 °C to +85 °C |
| | PCA9545AD,118 | SO20 | Reel 13" Q1/T1 *standard mark SMD | 2000 | T _{amb} = -40 °C to +85 °C |
| PCA9545APW | PCA9545APW,112 | TSSOP20 | Standard marking * IC's tube - DSC bulk pack | 1875 | T _{amb} = -40 °C to +85 °C |
| | PCA9545APW,118 | TSSOP20 | Reel 13" Q1/T1 *standard mark SMD | 2500 | T _{amb} = -40 °C to +85 °C |
| PCA9545BPW | PCA9545BPW,118 | TSSOP20 | Reel 13" Q1/T1 *standard mark SMD | 2500 | T _{amb} = -40 °C to +85 °C |
| PCA9545CPW | PCA9545CPW,118 | TSSOP20 | Reel 13" Q1/T1 *standard mark SMD | 2500 | T _{amb} = -40 °C to +85 °C |

4. Block diagram

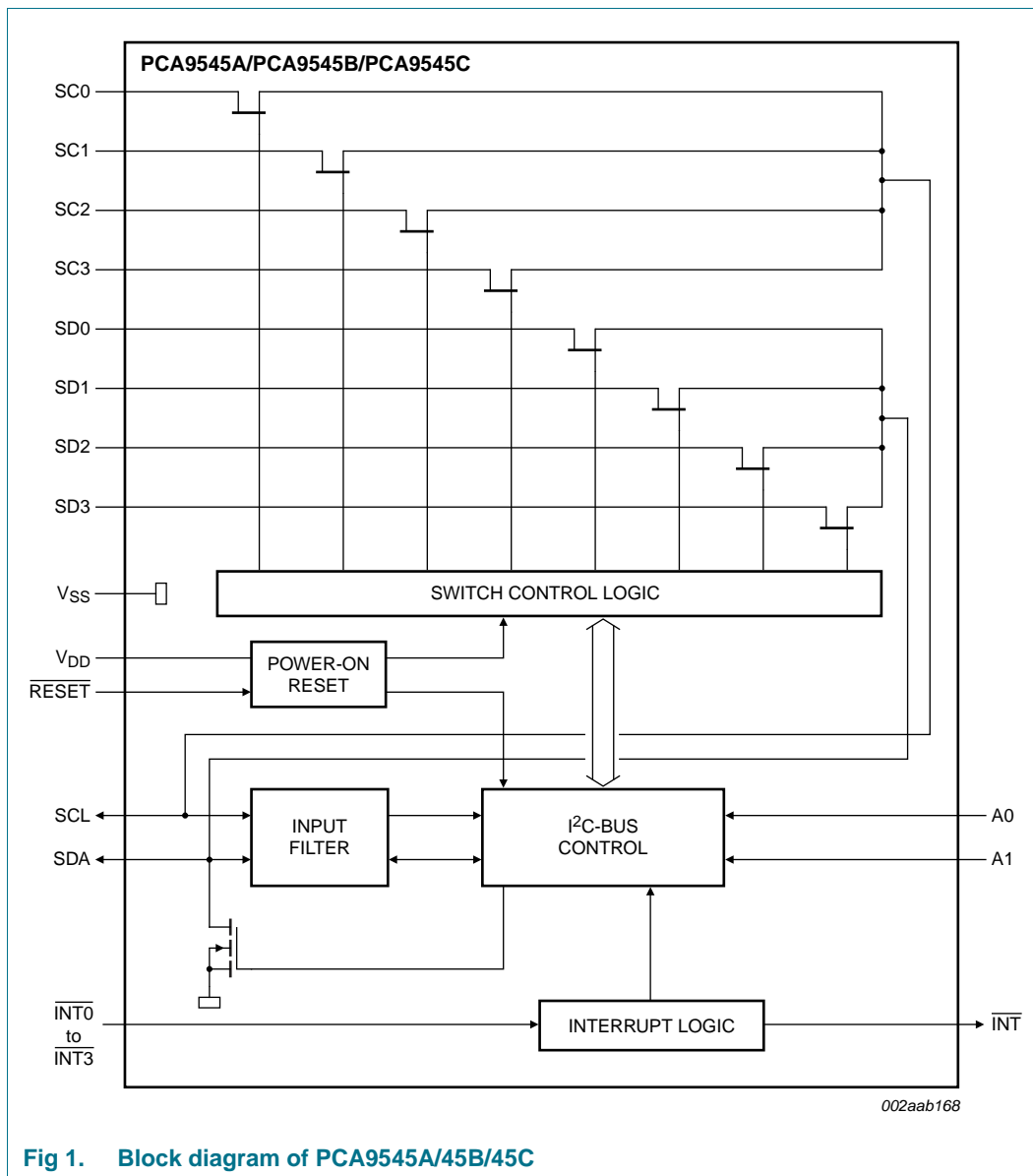


Fig 1. Block diagram of PCA9545A/45B/45C

5. Pinning information

5.1 Pinning

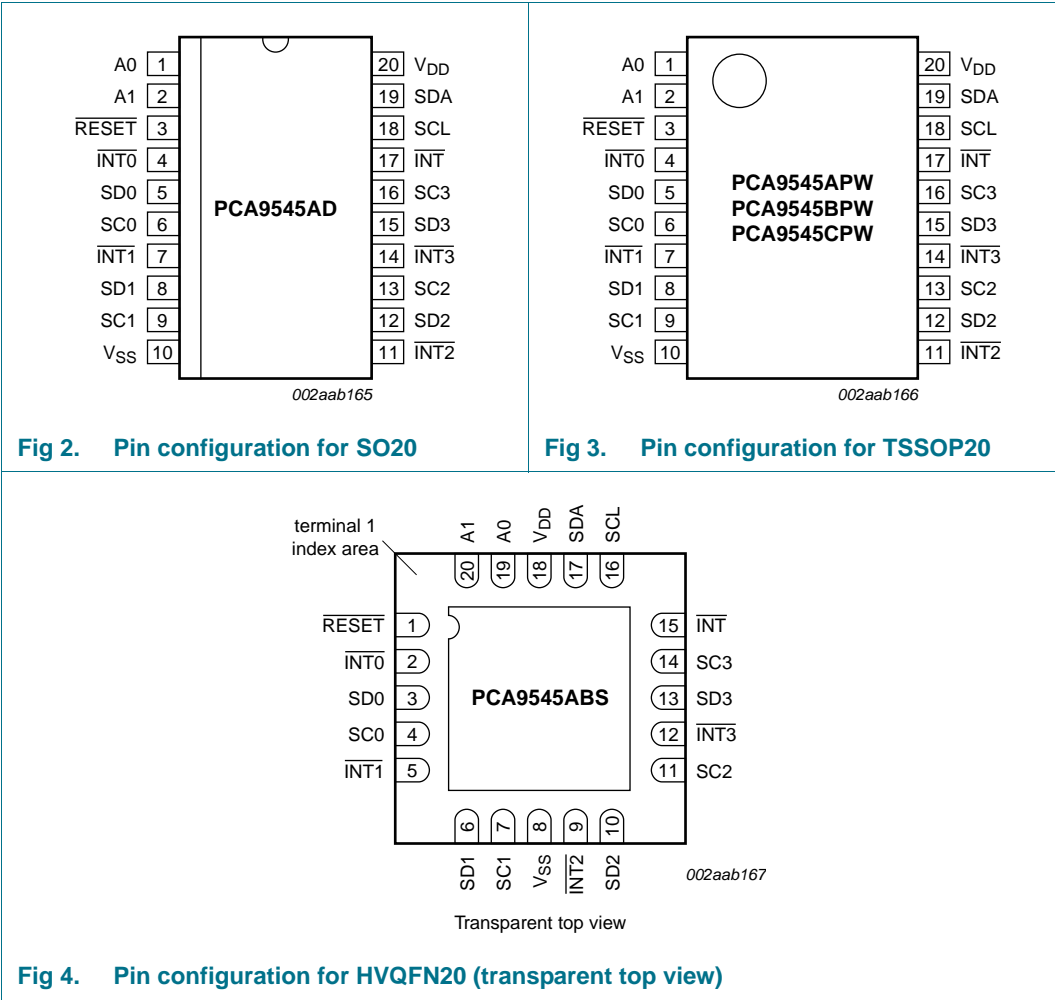


Fig 4. Pin configuration for HVQFN20 (transparent top view)

5.2 Pin description

Table 3. Pin description

| Symbol | Pin | | Description |
|---------------------------|---------------|------------------|------------------------------|
| | SO20, TSSOP20 | HVQFN20 | |
| A0 | 1 | 19 | address input 0 |
| A1 | 2 | 20 | address input 1 |
| $\overline{\text{RESET}}$ | 3 | 1 | active LOW reset input |
| $\overline{\text{INT0}}$ | 4 | 2 | active LOW interrupt input 0 |
| SD0 | 5 | 3 | serial data 0 |
| SC0 | 6 | 4 | serial clock 0 |
| $\overline{\text{INT1}}$ | 7 | 5 | active LOW interrupt input 1 |
| SD1 | 8 | 6 | serial data 1 |
| SC1 | 9 | 7 | serial clock 1 |
| V _{SS} | 10 | 8 ^[1] | supply ground |
| $\overline{\text{INT2}}$ | 11 | 9 | active LOW interrupt input 2 |
| SD2 | 12 | 10 | serial data 2 |
| SC2 | 13 | 11 | serial clock 2 |
| $\overline{\text{INT3}}$ | 14 | 12 | active LOW interrupt input 3 |
| SD3 | 15 | 13 | serial data 3 |
| SC3 | 16 | 14 | serial clock 3 |
| $\overline{\text{INT}}$ | 17 | 15 | active LOW interrupt output |
| SCL | 18 | 16 | serial clock line |
| SDA | 19 | 17 | serial data line |
| V _{DD} | 20 | 18 | supply voltage |

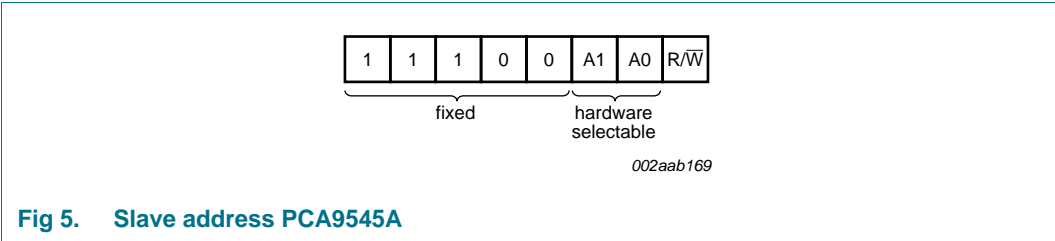
- [1] HVQFN20 package die supply ground is connected to both the V_{SS} pin and the exposed center pad. The V_{SS} pin must be connected to supply ground for proper device operation. For enhanced thermal, electrical, and board-level performance, the exposed pad needs to be soldered to the board using a corresponding thermal pad on the board, and for proper heat conduction through the board thermal vias need to be incorporated in the PCB in the thermal pad region.

6. Functional description

Refer to [Figure 1 “Block diagram of PCA9545A/45B/45C”](#).

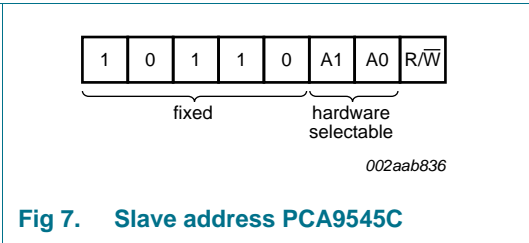
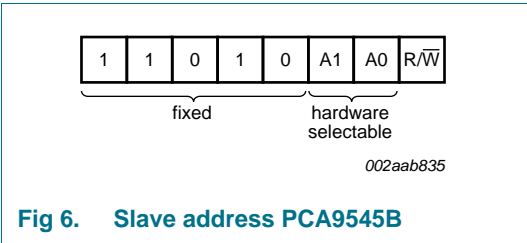
6.1 Device address

Following a START condition, the bus master must output the address of the slave it is accessing. The address of the PCA9545A is shown in [Figure 5](#). To conserve power, no internal pull-up resistors are incorporated on the hardware selectable address pins and they must be pulled HIGH or LOW.



The last bit of the slave address defines the operation to be performed. When set to logic 1, a read is selected while a logic 0 selects a write operation.

The PCA9545BPW and PCA9545CPW are alternate address versions if needed for larger systems or to resolve conflicts. The data sheet will reference the PCA9545A, but the PCA9545B and PCA9545C function identically except for the slave address.



6.2 Control register

Following the successful acknowledgement of the slave address, the bus master will send a byte to the PCA9545A/45B/45C, which will be stored in the control register. If multiple bytes are received by the PCA9545A/45B/45C, it will save the last byte received. This register can be written and read via the I²C-bus.

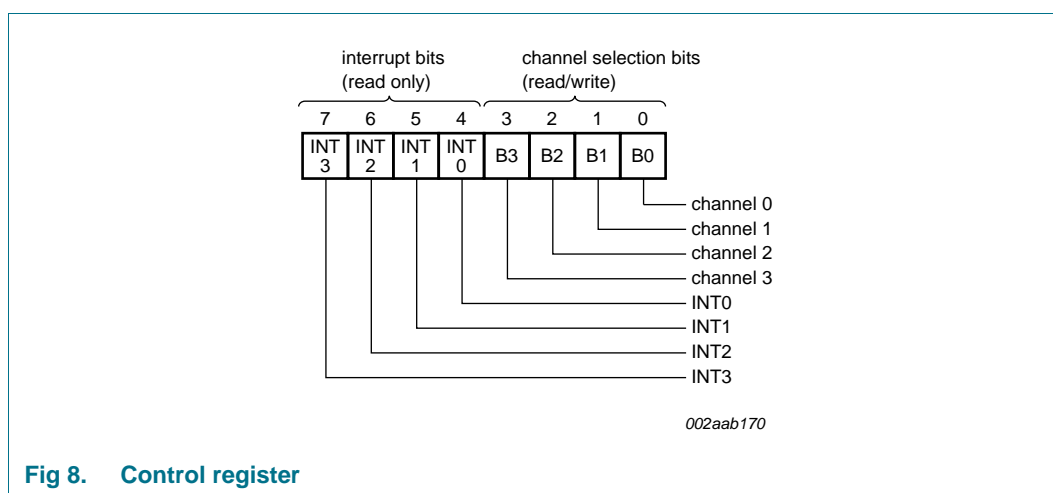


Fig 8. Control register

6.2.1 Control register definition

One or several SCx/SDx downstream pair, or channel, is selected by the contents of the control register. This register is written after the PCA9545A/45B/45C has been addressed. The 4 LSBs of the control byte are used to determine which channel is to be selected. When a channel is selected, the channel will become active after a STOP condition has been placed on the I²C-bus. This ensures that all SCx/SDx lines will be in a HIGH state when the channel is made active, so that no false conditions are generated at the time of connection.

Table 4. Control register: write (channel selection); read (channel status)

| INT3 | INT2 | INT1 | INT0 | B3 | B2 | B1 | B0 | Command |
|------|------|------|------|----|----|----|----|--|
| X | X | X | X | X | X | X | 0 | channel 0 disabled |
| | | | | | | | 1 | channel 0 enabled |
| X | X | X | X | X | X | 0 | X | channel 1 disabled |
| | | | | | | 1 | | channel 1 enabled |
| X | X | X | X | X | 0 | X | X | channel 2 disabled |
| | | | | | 1 | | | channel 2 enabled |
| X | X | X | X | 0 | X | X | X | channel 3 disabled |
| | | | | 1 | | | | channel 3 enabled |
| 0 | 0 | 0 | 0 | 0 | 0 | 0 | 0 | no channel selected; power-up/reset default state |

Remark: Several channels can be enabled at the same time. Example: B3 = 0, B2 = 1, B1 = 1, B0 = 0, means that channel 0 and channel 3 are disabled and channel 1 and channel 2 are enabled. Care should be taken not to exceed the maximum bus capacity.

6.2.2 Interrupt handling

The PCA9545A/45B/45C provides 4 interrupt inputs, one for each channel, and one open-drain interrupt output. When an interrupt is generated by any device, it will be detected by the PCA9545A/45B/45C and the interrupt output will be driven LOW. The channel does not need to be active for detection of the interrupt. A bit is also set in the control register.

Bit 4 through bit 7 of the control register corresponds to channel 0 through channel 3 of the PCA9545A/45B/45C, respectively. Therefore, if an interrupt is generated by any device connected to channel 1, the state of the interrupt inputs is loaded into the control register when a read is accomplished. Likewise, an interrupt on any device connected to channel 0 would cause bit 4 of the control register to be set on the read. The master can then address the PCA9545A/45B/45C and read the contents of the control register to determine which channel contains the device generating the interrupt. The master can then reconfigure the PCA9545A/45B/45C to select this channel, and locate the device generating the interrupt and clear it.

It should be noted that more than one device can provide an interrupt on a channel, so it is up to the master to ensure that all devices on a channel are interrogated for an interrupt.

The interrupt inputs may be used as general-purpose inputs if the interrupt function is not required.

If unused, interrupt input(s) must be connected to V_{DD} through a pull-up resistor.

Table 5. Control register: Read — interrupt

| INT3 | INT2 | INT1 | INT0 | B3 | B2 | B1 | B0 | Command |
|--|--|--|--|----|----|----|----|---|
| X | X | X | $\begin{smallmatrix} 0 \\ 1 \end{smallmatrix}$ | X | X | X | X | no interrupt on channel 0 interrupt on channel 0 |
| X | X | $\begin{smallmatrix} 0 \\ 1 \end{smallmatrix}$ | X | X | X | X | X | no interrupt on channel 1 interrupt on channel 1 |
| X | $\begin{smallmatrix} 0 \\ 1 \end{smallmatrix}$ | X | X | X | X | X | X | no interrupt on channel 2 interrupt on channel 2 |
| $\begin{smallmatrix} 0 \\ 1 \end{smallmatrix}$ | X | X | X | X | X | X | X | no interrupt on channel 3 interrupt on channel 3 |

Remark: Several interrupts can be active at the same time. Example: INT3 = 0, INT2 = 1, INT1 = 1, INT0 = 0, means that there is no interrupt on channel 0 and channel 3, and there is interrupt on channel 1 and channel 2.

6.3 RESET input

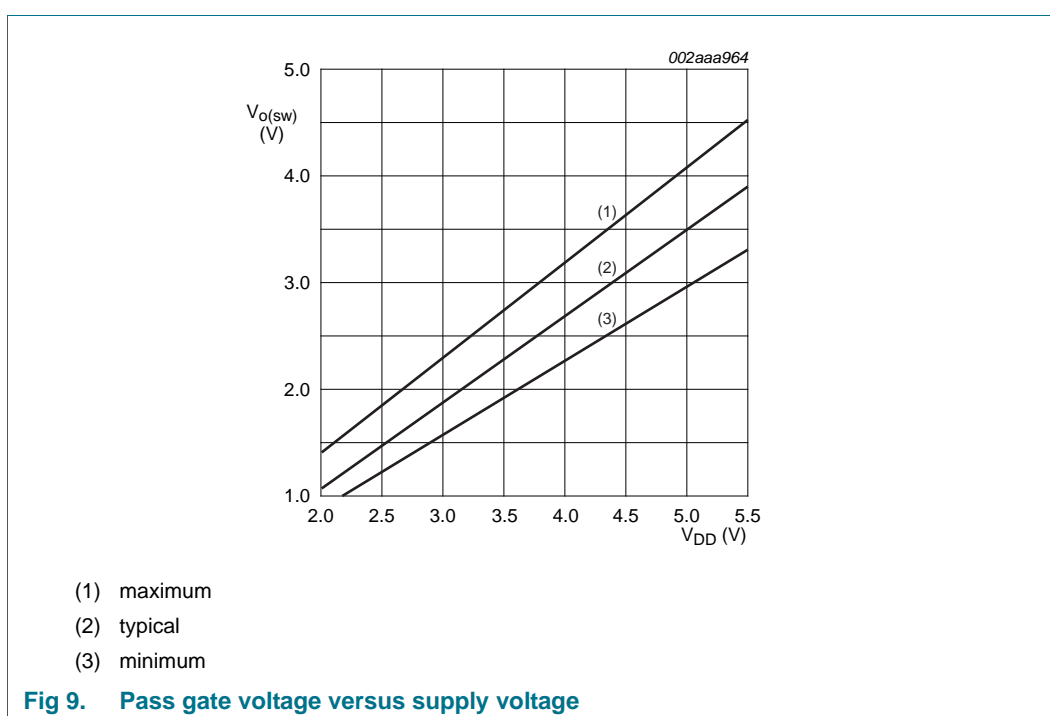
The $\overline{\text{RESET}}$ input is an active LOW signal which may be used to recover from a bus fault condition. By asserting this signal LOW for a minimum of $t_{w(\text{rst})L}$, the PCA9545A/45B/45C will reset its registers and I²C-bus state machine and will deselect all channels. The $\overline{\text{RESET}}$ input must be connected to V_{DD} through a pull-up resistor.

6.4 Power-on reset

When power is applied to V_{DD} , an internal Power-On Reset (POR) holds the PCA9545A/45B/45C in a reset condition until V_{DD} has reached V_{POR} . At this point, the reset condition is released and the PCA9545A/45B/45C registers and I²C-bus state machine are initialized to their default states (all zeroes) causing all the channels to be deselected. Thereafter, V_{DD} must be lowered below 0.2 V to reset the device.

6.5 Voltage translation

The pass gate transistors of the PCA9545A/45B/45C are constructed such that the V_{DD} voltage can be used to limit the maximum voltage that will be passed from one I²C-bus to another.



[Figure 9](#) shows the voltage characteristics of the pass gate transistors (note that the graph was generated using the data specified in [Section 11 “Static characteristics”](#) of this data sheet). In order for the PCA9545A/45B/45C to act as a voltage translator, the $V_{O(sw)}$ voltage should be equal to, or lower than the lowest bus voltage. For example, if the main bus was running at 5 V, and the downstream buses were 3.3 V and 2.7 V, then $V_{O(sw)}$ should be equal to or below 2.7 V to effectively clamp the downstream bus voltages. Looking at [Figure 9](#), we see that $V_{O(sw)(max)}$ will be at 2.7 V when the PCA9545A/45B/45C supply voltage is 3.5 V or lower, so the PCA9545A/45B/45C supply voltage could be set to 3.3 V. Pull-up resistors can then be used to bring the bus voltages to their appropriate levels (see [Figure 16](#)).

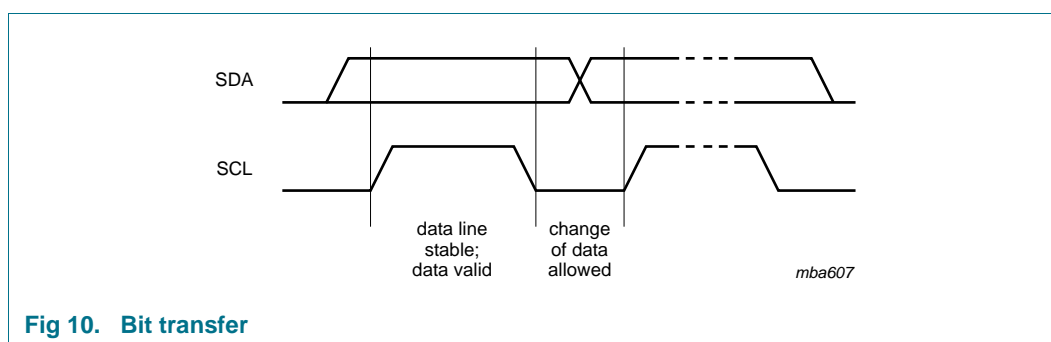
More Information can be found in Application Note *AN262: PCA954X family of I²C/SMBus multiplexers and switches*.

7. Characteristics of the I²C-bus

The I²C-bus is for 2-way, 2-line communication between different ICs or modules. The two lines are a serial data line (SDA) and a serial clock line (SCL). Both lines must be connected to a positive supply via a pull-up resistor when connected to the output stages of a device. Data transfer may be initiated only when the bus is not busy.

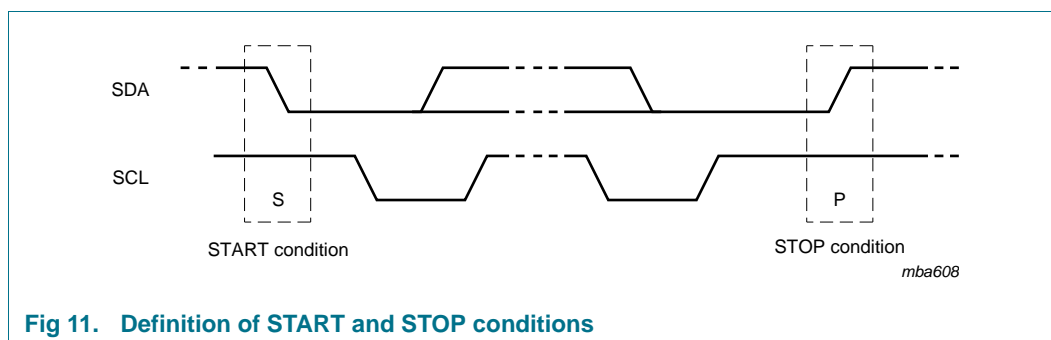
7.1 Bit transfer

One data bit is transferred during each clock pulse. The data on the SDA line must remain stable during the HIGH period of the clock pulse as changes in the data line at this time will be interpreted as control signals (see [Figure 10](#)).



7.2 START and STOP conditions

Both data and clock lines remain HIGH when the bus is not busy. A HIGH-to-LOW transition of the data line, while the clock is HIGH is defined as the START condition (S). A LOW-to-HIGH transition of the data line while the clock is HIGH is defined as the STOP condition (P) (see [Figure 11](#)).



7.3 System configuration

A device generating a message is a 'transmitter', a device receiving is the 'receiver'. The device that controls the message is the 'master' and the devices which are controlled by the master are the 'slaves' (see [Figure 12](#)).

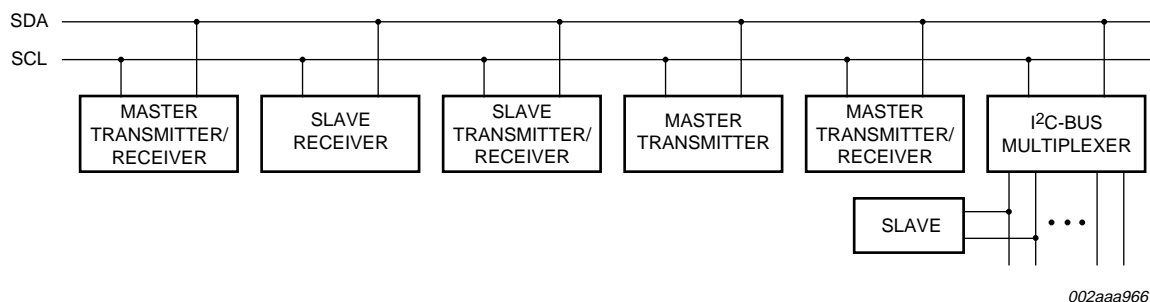


Fig 12. System configuration

7.4 Acknowledge

The number of data bytes transferred between the START and the STOP conditions from transmitter to receiver is not limited. Each byte of eight bits is followed by one acknowledge bit. The acknowledge bit is a HIGH level put on the bus by the transmitter, whereas the master generates an extra acknowledge related clock pulse.

A slave receiver which is addressed must generate an acknowledge after the reception of each byte. Also a master must generate an acknowledge after the reception of each byte that has been clocked out of the slave transmitter. The device that acknowledges has to pull down the SDA line during the acknowledge clock pulse, so that the SDA line is stable LOW during the HIGH period of the acknowledge related clock pulse; set-up and hold times must be taken into account.

A master receiver must signal an end of data to the transmitter by not generating an acknowledge on the last byte that has been clocked out of the slave. In this event, the transmitter must leave the data line HIGH to enable the master to generate a STOP condition.

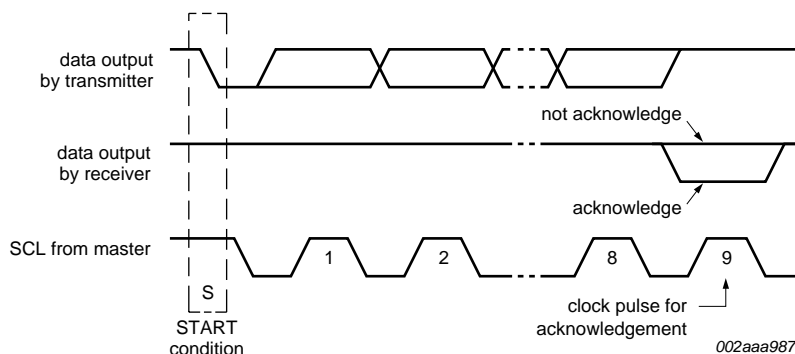
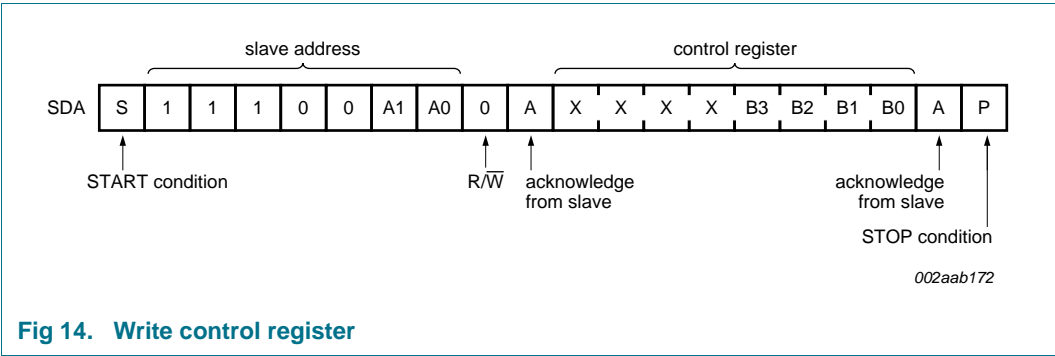


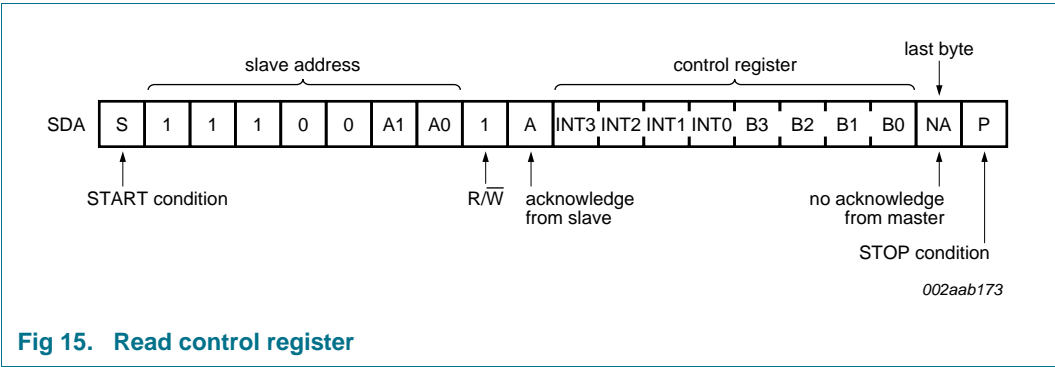
Fig 13. Acknowledgement on the I²C-bus

7.5 Bus transactions

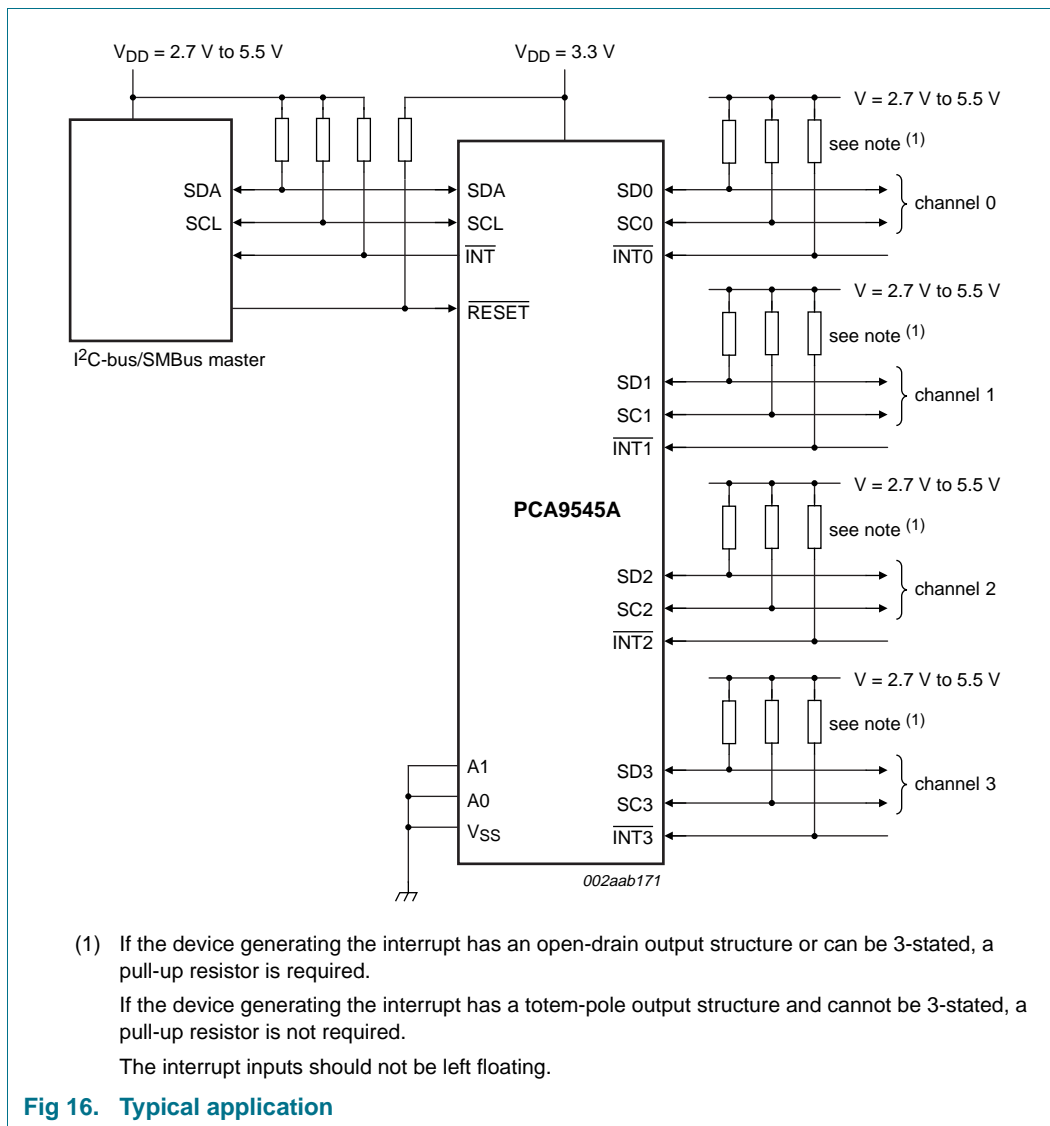
Data is transmitted to the PCA9545A/45B/45C control register using the Write mode as shown in [Figure 14](#).



Data is read from PCA9545A/45B/45C using the Read mode as shown in [Figure 15](#).



8. Application design-in information



9. Limiting values

Table 6. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to V_{SS} (ground = 0 V).

| Symbol | Parameter | Conditions | Min | Max | Unit |
|---------------------|------------------------------|------------|------|------|------|
| V _{DD} | supply voltage | | −0.5 | +7.0 | V |
| V _I | input voltage | | −0.5 | +7.0 | V |
| I _I | input current | | - | ±20 | mA |
| I _O | output current | | - | ±25 | mA |
| I _{DD} | supply current | | - | ±100 | mA |
| I _{SS} | ground supply current | | - | ±100 | mA |
| P _{tot} | total power dissipation | | - | 400 | mW |
| T _{j(max)} | maximum junction temperature | [1] | - | 125 | °C |
| T _{stg} | storage temperature | | −60 | +150 | °C |
| T _{amb} | ambient temperature | operating | −40 | +85 | °C |

[1] The performance capability of a high-performance integrated circuit in conjunction with its thermal environment can create junction temperatures which are detrimental to reliability. The maximum junction temperature of this integrated circuit should not exceed 125 °C.

10. Thermal characteristics

Table 7. Thermal characteristics

| Symbol | Parameter | Conditions | Typ | Unit |
|----------------------|---|-----------------|-----|------|
| R _{th(j-a)} | thermal resistance from junction to ambient | HVQFN20 package | 32 | °C/W |
| | | SO20 package | 90 | °C/W |
| | | TSSOP20 package | 146 | °C/W |

11. Static characteristics

Table 8. Static characteristics at $V_{DD} = 2.3\text{ V}$ to 3.6 V

$V_{SS} = 0\text{ V}$; $T_{amb} = -40\text{ }^{\circ}\text{C}$ to $+85\text{ }^{\circ}\text{C}$; unless otherwise specified. See [Table 9 on page 16](#) for $V_{DD} = 4.5\text{ V}$ to 5.5 V ^[1].

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|--|---------------------------|---|------------------|-----|---------------|---------------|
| Supply | | | | | | |
| V_{DD} | supply voltage | | 2.3 | - | 3.6 | V |
| I_{DD} | supply current | Operating mode; $V_{DD} = 3.6\text{ V}$; no load; $V_I = V_{DD}$ or V_{SS} ; $f_{SCL} = 100\text{ kHz}$ | - | 10 | 30 | μA |
| I_{stb} | standby current | Standby mode; $V_{DD} = 3.6\text{ V}$; no load; $V_I = V_{DD}$ or V_{SS} | - | 0.1 | 1 | μA |
| V_{POR} | power-on reset voltage | no load; $V_I = V_{DD}$ or V_{SS} | ^[2] - | 1.6 | 2.1 | V |
| Input SCL; input/output SDA | | | | | | |
| V_{IL} | LOW-level input voltage | | -0.5 | - | +0.3 V_{DD} | V |
| V_{IH} | HIGH-level input voltage | | 0.7 V_{DD} | - | 6 | V |
| I_{OL} | LOW-level output current | $V_{OL} = 0.4\text{ V}$ | 3 | 7 | - | mA |
| | | $V_{OL} = 0.6\text{ V}$ | 6 | 10 | - | mA |
| I_L | leakage current | $V_I = V_{DD}$ or V_{SS} | -1 | - | +1 | μA |
| C_i | input capacitance | $V_I = V_{SS}$ | - | 10 | 13 | pF |
| Select inputs A0, A1, INT0 to INT3, RESET | | | | | | |
| V_{IL} | LOW-level input voltage | | -0.5 | - | +0.3 V_{DD} | V |
| V_{IH} | HIGH-level input voltage | | 0.7 V_{DD} | - | 6 | V |
| I_{LI} | input leakage current | pin at V_{DD} or V_{SS} | -1 | - | +1 | μA |
| C_i | input capacitance | $V_I = V_{SS}$ | - | 1.6 | 3 | pF |
| Pass gate | | | | | | |
| R_{on} | ON-state resistance | $V_{DD} = 3.6\text{ V}$; $V_O = 0.4\text{ V}$; $I_O = 15\text{ mA}$ | 5 | 11 | 30 | Ω |
| | | $V_{DD} = 2.3\text{ V}$ to 2.7 V ; $V_O = 0.4\text{ V}$; $I_O = 10\text{ mA}$ | 7 | 16 | 55 | Ω |
| $V_{O(sw)}$ | switch output voltage | $V_{i(sw)} = V_{DD} = 3.3\text{ V}$; $I_{o(sw)} = -100\text{ }\mu\text{A}$ | - | 1.9 | - | V |
| | | $V_{i(sw)} = V_{DD} = 3.0\text{ V}$ to 3.6 V ; $I_{o(sw)} = -100\text{ }\mu\text{A}$ | 1.6 | - | 2.8 | V |
| | | $V_{i(sw)} = V_{DD} = 2.5\text{ V}$; $I_{o(sw)} = -100\text{ }\mu\text{A}$ | - | 1.5 | - | V |
| | | $V_{i(sw)} = V_{DD} = 2.3\text{ V}$ to 2.7 V ; $I_{o(sw)} = -100\text{ }\mu\text{A}$ | 1.1 | - | 2.0 | V |
| I_L | leakage current | $V_I = V_{DD}$ or V_{SS} | -1 | - | +1 | μA |
| C_{io} | input/output capacitance | $V_I = V_{SS}$ | - | 3 | 5 | pF |
| INT output | | | | | | |
| I_{OL} | LOW-level output current | $V_{OL} = 0.4\text{ V}$ | 3 | - | - | mA |
| I_{OH} | HIGH-level output current | | - | - | +10 | μA |

[1] For operation between published voltage ranges, refer to the worst-case parameter in both ranges.

[2] V_{DD} must be lowered to 0.2 V in order to reset part.

Table 9. Static characteristics at $V_{DD} = 4.5\text{ V}$ to 5.5 V

$V_{SS} = 0\text{ V}$; $T_{amb} = -40\text{ }^{\circ}\text{C}$ to $+85\text{ }^{\circ}\text{C}$; unless otherwise specified. See [Table 8 on page 15](#) for $V_{DD} = 2.3\text{ V}$ to 3.6 V [\[1\]](#).

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|--|---------------------------|--|-----------------------|-----|--------------|---------------|
| Supply | | | | | | |
| V_{DD} | supply voltage | | 4.5 | - | 5.5 | V |
| I_{DD} | supply current | Operating mode; $V_{DD} = 5.5\text{ V}$; no load; $V_I = V_{DD}$ or V_{SS} ; $f_{SCL} = 100\text{ kHz}$ | - | 25 | 100 | μA |
| I_{stb} | standby current | Standby mode; $V_{DD} = 5.5\text{ V}$; no load; $V_I = V_{DD}$ or V_{SS} | - | 0.3 | 1 | μA |
| V_{POR} | power-on reset voltage | no load; $V_I = V_{DD}$ or V_{SS} | [2] - | 1.7 | 2.1 | V |
| Input SCL; input/output SDA | | | | | | |
| V_{IL} | LOW-level input voltage | | -0.5 | - | $+0.3V_{DD}$ | V |
| V_{IH} | HIGH-level input voltage | | $0.7V_{DD}$ | - | 6 | V |
| I_{OL} | LOW-level output current | $V_{OL} = 0.4\text{ V}$ | 3 | - | - | mA |
| | | $V_{OL} = 0.6\text{ V}$ | 6 | - | - | mA |
| I_L | leakage current | $V_I = V_{SS}$ | -1 | - | +1 | μA |
| C_i | input capacitance | $V_I = V_{SS}$ | - | 10 | 13 | pF |
| Select inputs A0, A1, INT0 to INT3, RESET | | | | | | |
| V_{IL} | LOW-level input voltage | | -0.5 | - | $+0.3V_{DD}$ | V |
| V_{IH} | HIGH-level input voltage | | $0.7V_{DD}$ | - | 6 | V |
| I_{LI} | input leakage current | $V_I = V_{DD}$ or V_{SS} | -1 | - | +1 | μA |
| C_i | input capacitance | $V_I = V_{SS}$ | - | 2 | 5 | pF |
| Pass gate | | | | | | |
| R_{on} | ON-state resistance | $V_{DD} = 4.5\text{ V}$ to 5.5 V ; $V_O = 0.4\text{ V}$; $I_O = 15\text{ mA}$ | 4 | 9 | 24 | Ω |
| $V_{o(sw)}$ | switch output voltage | $V_{i(sw)} = V_{DD} = 5.0\text{ V}$; $I_{o(sw)} = -100\text{ }\mu\text{A}$ | - | 3.6 | - | V |
| | | $V_{i(sw)} = V_{DD} = 4.5\text{ V}$ to 5.5 V ; $I_{o(sw)} = -100\text{ }\mu\text{A}$ | 2.6 | - | 4.5 | V |
| I_L | leakage current | $V_I = V_{DD}$ or V_{SS} | -1 | - | +1 | μA |
| C_{io} | input/output capacitance | $V_I = V_{SS}$ | - | 3 | 5 | pF |
| INT output | | | | | | |
| I_{OL} | LOW-level output current | $V_{OL} = 0.4\text{ V}$ | 3 | - | - | mA |
| I_{OH} | HIGH-level output current | | - | - | +10 | μA |

[1] For operation between published voltage ranges, refer to the worst-case parameter in both ranges.

[2] V_{DD} must be lowered to 0.2 V in order to reset part.

12. Dynamic characteristics

Table 10. Dynamic characteristics

| Symbol | Parameter | Conditions | Standard-mode I ² C-bus | | Fast-mode I ² C-bus | | Unit |
|----------------------------|--|-----------------------------------|------------------------------------|--------------------|---------------------------------------|--------------------|--------|
| | | | Min | Max | Min | Max | |
| t _{PD} | propagation delay | from SDA to SDx, or SCL to SCx | - | 0.3 ^[1] | - | 0.3 ^[1] | ns |
| f _{SCL} | SCL clock frequency | | 0 | 100 | 0 | 400 | kHz |
| t _{BUF} | bus free time between a STOP and START condition | | 4.7 | - | 1.3 | - | μs |
| t _{HD;STA} | hold time (repeated) START condition | ^[2] | 4.0 | - | 0.6 | - | μs |
| t _{LOW} | LOW period of the SCL clock | | 4.7 | - | 1.3 | - | μs |
| t _{HIGH} | HIGH period of the SCL clock | | 4.0 | - | 0.6 | - | μs |
| t _{SU;STA} | set-up time for a repeated START condition | | 4.7 | - | 0.6 | - | μs |
| t _{SU;STO} | set-up time for STOP condition | | 4.0 | - | 0.6 | - | μs |
| t _{HD;DAT} | data hold time | | 0 ^[3] | 3.45 | 0 ^[3] | 0.9 | μs |
| t _{SU;DAT} | data set-up time | | 250 | - | 100 | - | ns |
| t _r | rise time of both SDA and SCL signals | | - | 1000 | 20 + 0.1C _b ^[4] | 300 | ns |
| t _f | fall time of both SDA and SCL signals | | - | 300 | 20 + 0.1C _b ^[4] | 300 | ns |
| C _b | capacitive load for each bus line | | - | 400 | - | 400 | pF |
| t _{SP} | pulse width of spikes that must be suppressed by the input filter | | - | 50 | - | 50 | ns |
| t _{VD;DAT} | data valid time | HIGH-to-LOW | ^[5] | - | 1 | - | 1 μs |
| | | LOW-to-HIGH | ^[5] | - | 0.6 | - | 0.6 μs |
| t _{VD;ACK} | data valid acknowledge time | | - | 1 | - | 1 | μs |
| INT | | | | | | | |
| t _{v(INTnN-INTN)} | valid time from $\overline{\text{INTn}}$ to $\overline{\text{INT}}$ signal | | - | 4 | - | 4 | μs |
| t _{d(INTnN-INTN)} | delay time from $\overline{\text{INTn}}$ to $\overline{\text{INT}}$ inactive | | - | 2 | - | 2 | μs |
| t _{w(rej)L} | LOW-level rejection time | $\overline{\text{INTn}}$ inputs | 1 | - | 1 | - | μs |
| t _{w(rej)H} | HIGH-level rejection time | $\overline{\text{INTn}}$ inputs | 0.5 | - | 0.5 | - | μs |
| RESET | | | | | | | |
| t _{w(rst)L} | LOW-level reset time | | 4 | - | 4 | - | ns |
| t _{rst} | reset time | SDA clear | 500 | - | 500 | - | ns |
| t _{REC;STA} | recovery time to START condition | | 0 | - | 0 | - | ns |

[1] Pass gate propagation delay is calculated from the 20 Ω typical R_{on} and the 15 pF load capacitance.

[2] After this period, the first clock pulse is generated.

[3] A device must internally provide a hold time of at least 300 ns for the SDA signal (referred to the V_{IH(min)} of the SCL signal) in order to bridge the undefined region of the falling edge of SCL.

[4] C_b = total capacitance of one bus line in pF.

[5] Measurements taken with 1 kΩ pull-up resistor and 50 pF load.

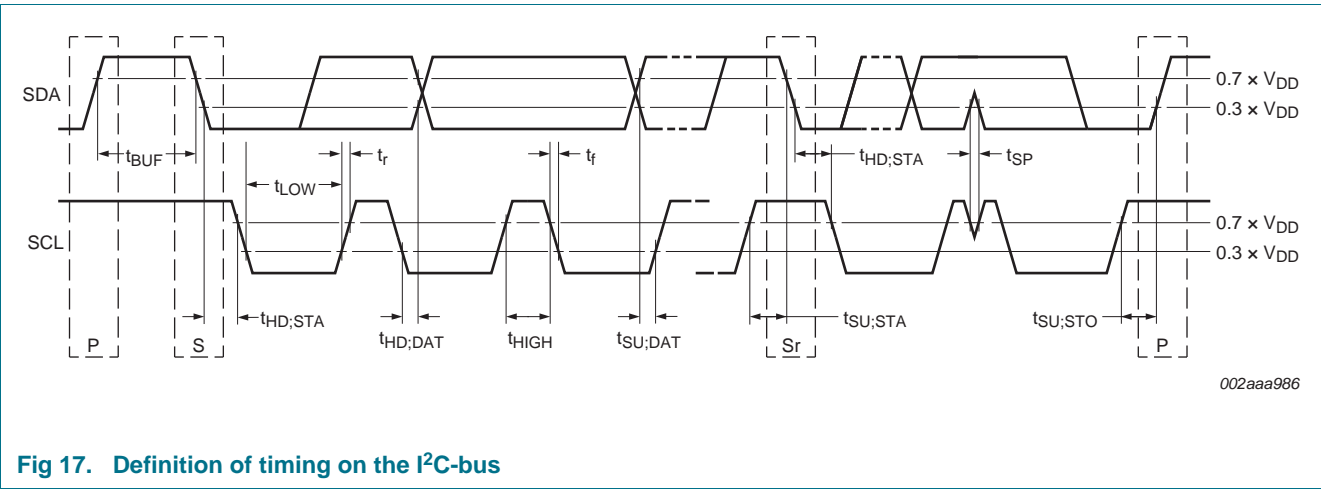


Fig 17. Definition of timing on the I²C-bus

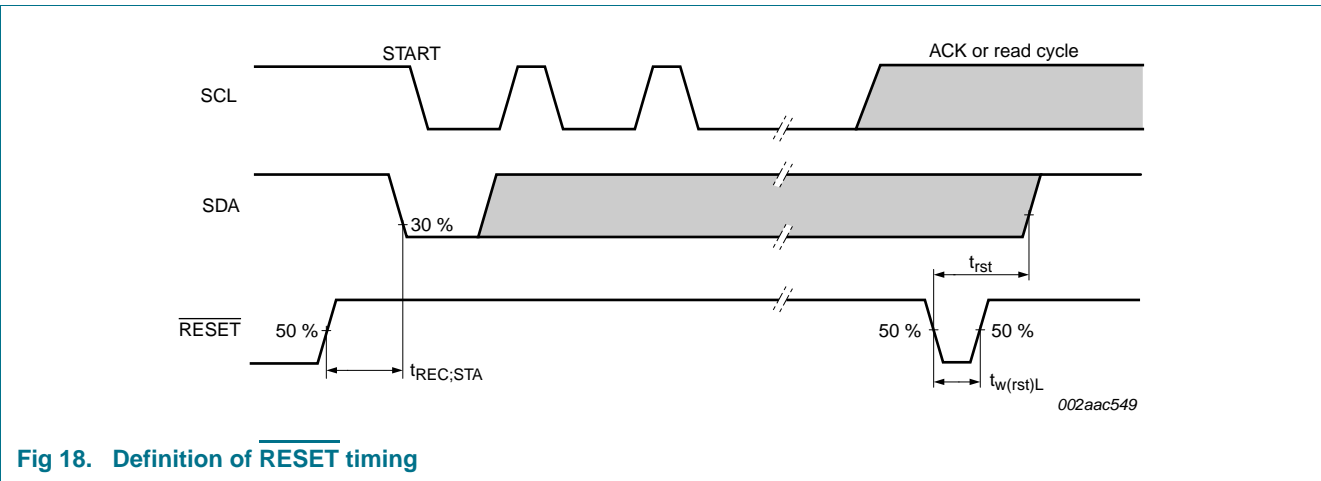


Fig 18. Definition of RESET timing

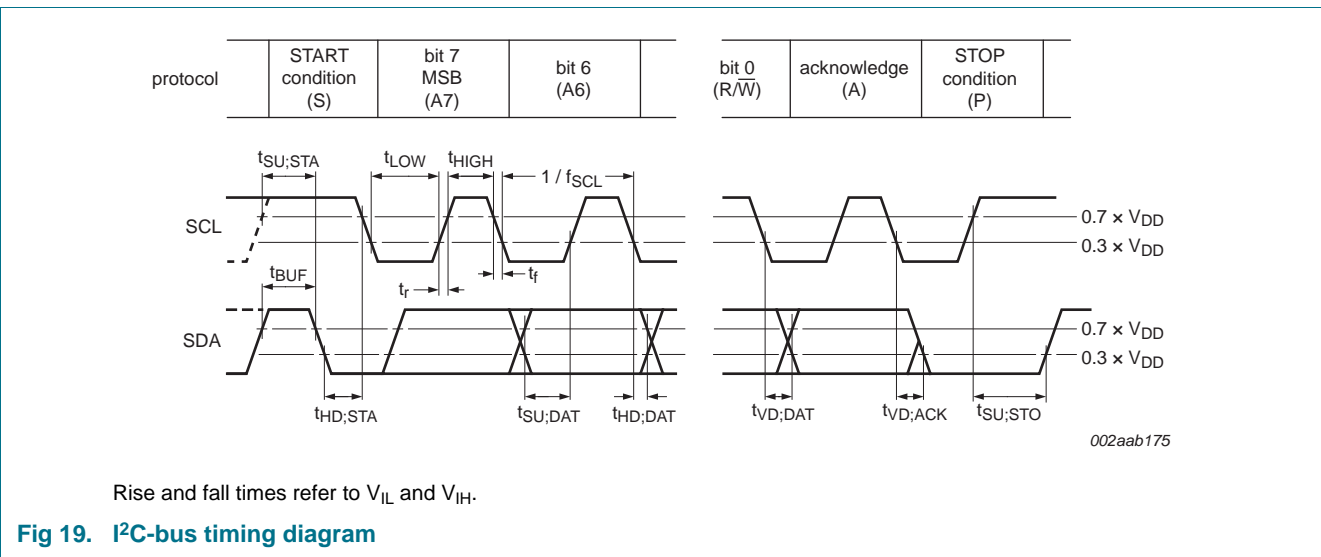
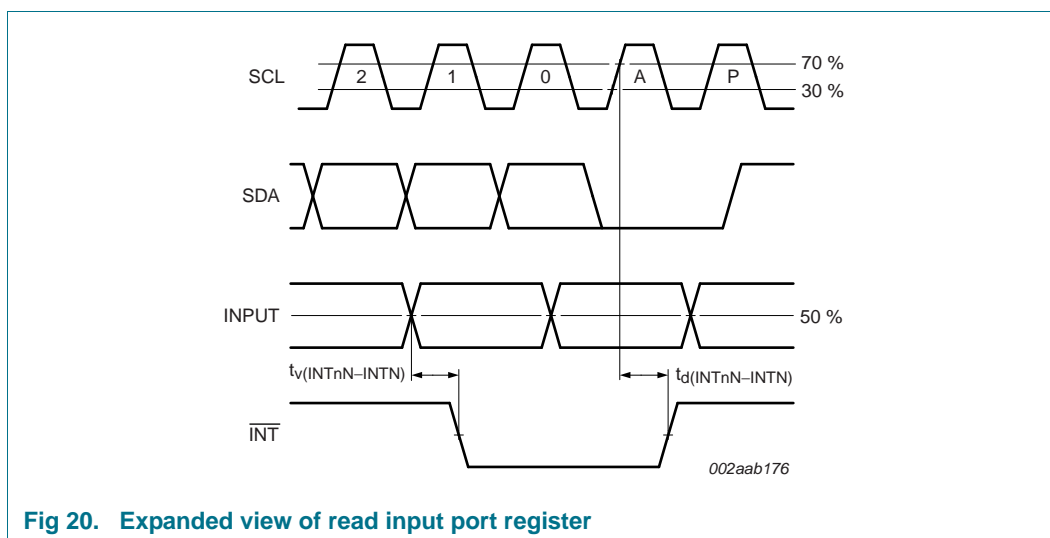
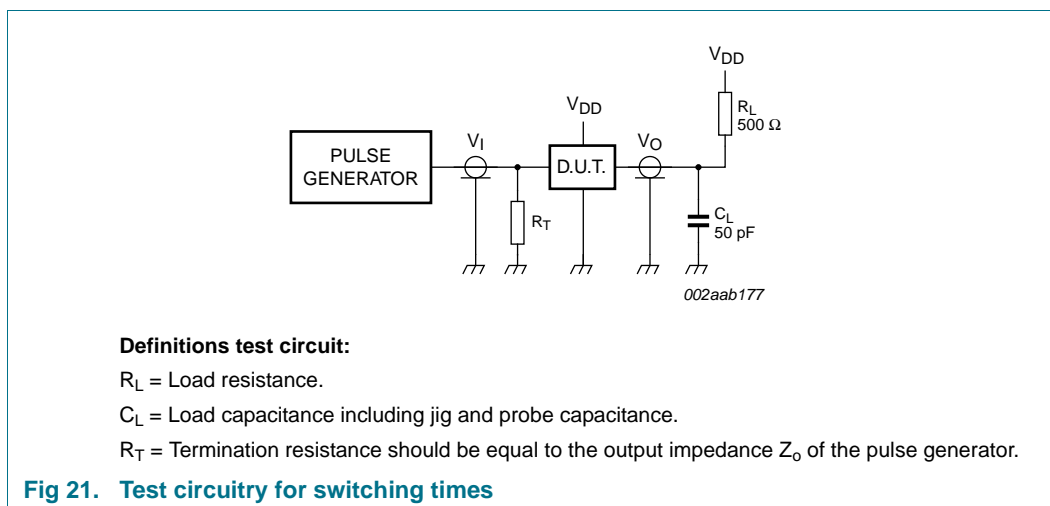


Fig 19. I²C-bus timing diagram



13. Test information



14. Package outline

SO20: plastic small outline package; 20 leads; body width 7.5 mm

SOT163-1

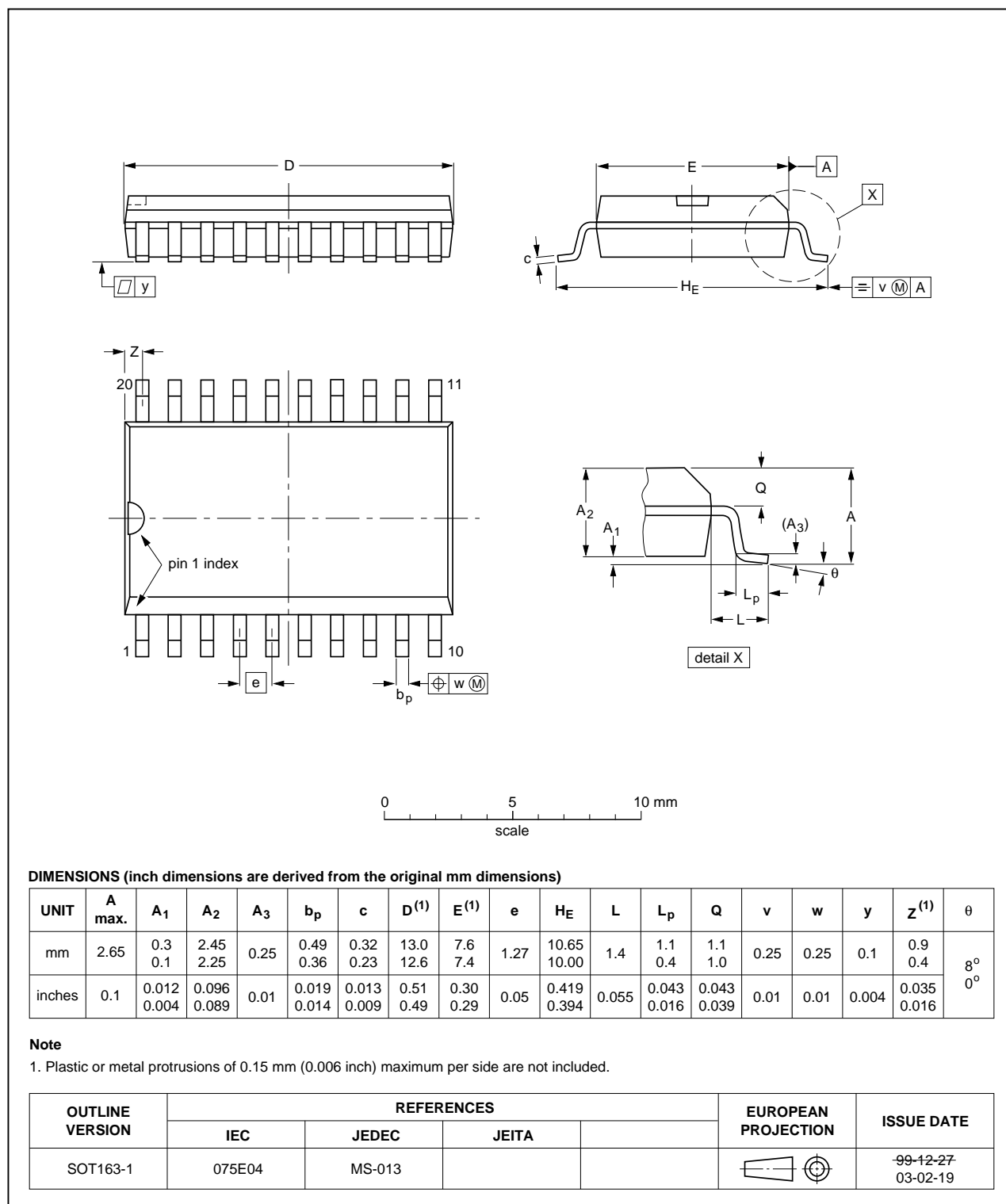


Fig 22. Package outline SOT163-1 (SO20)

TSSOP20: plastic thin shrink small outline package; 20 leads; body width 4.4 mm

SOT360-1

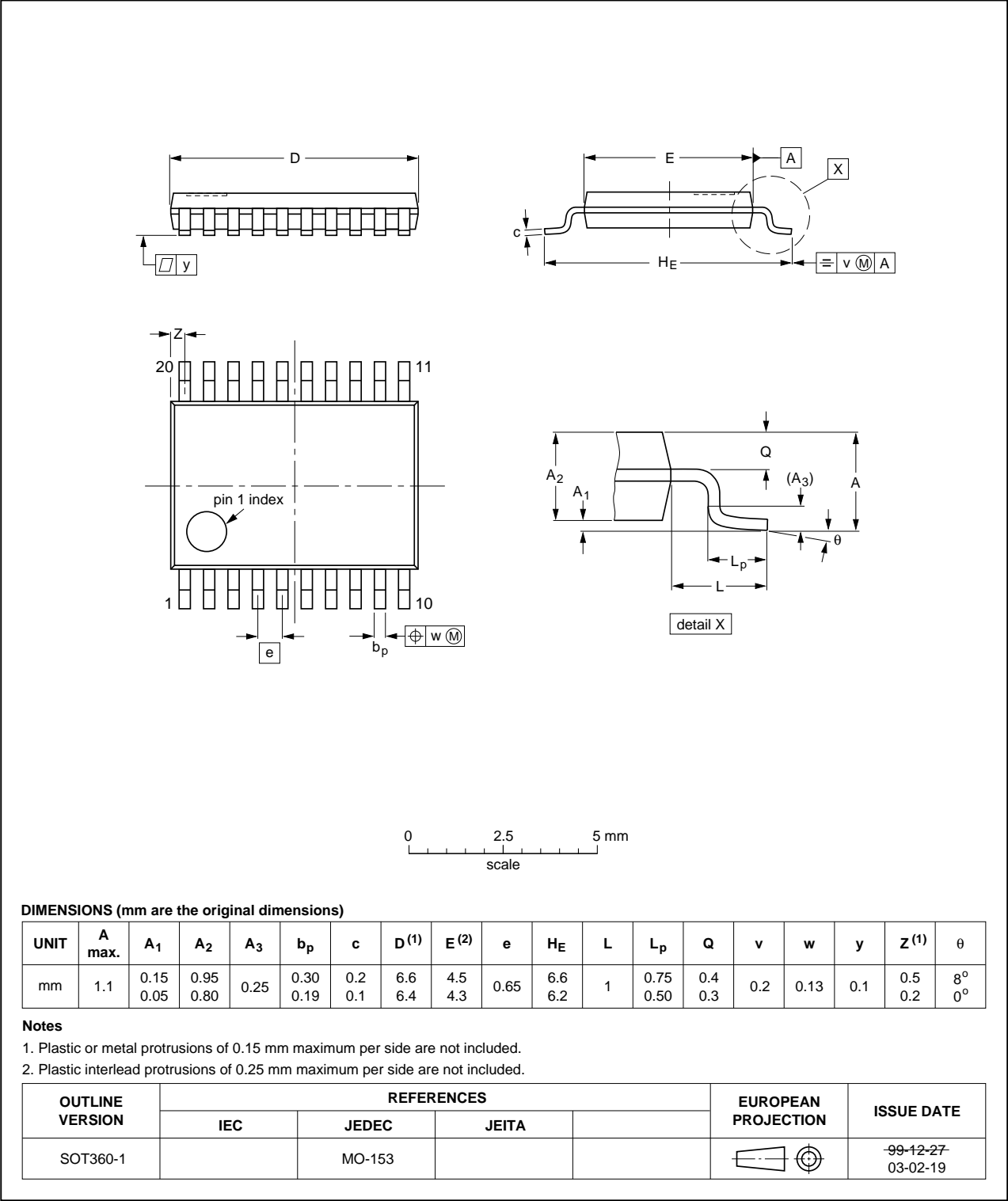


Fig 23. Package outline SOT360-1 (TSSOP20)

HVQFN20: plastic thermal enhanced very thin quad flat package; no leads;
20 terminals; body 5 x 5 x 0.85 mm

SOT662-1

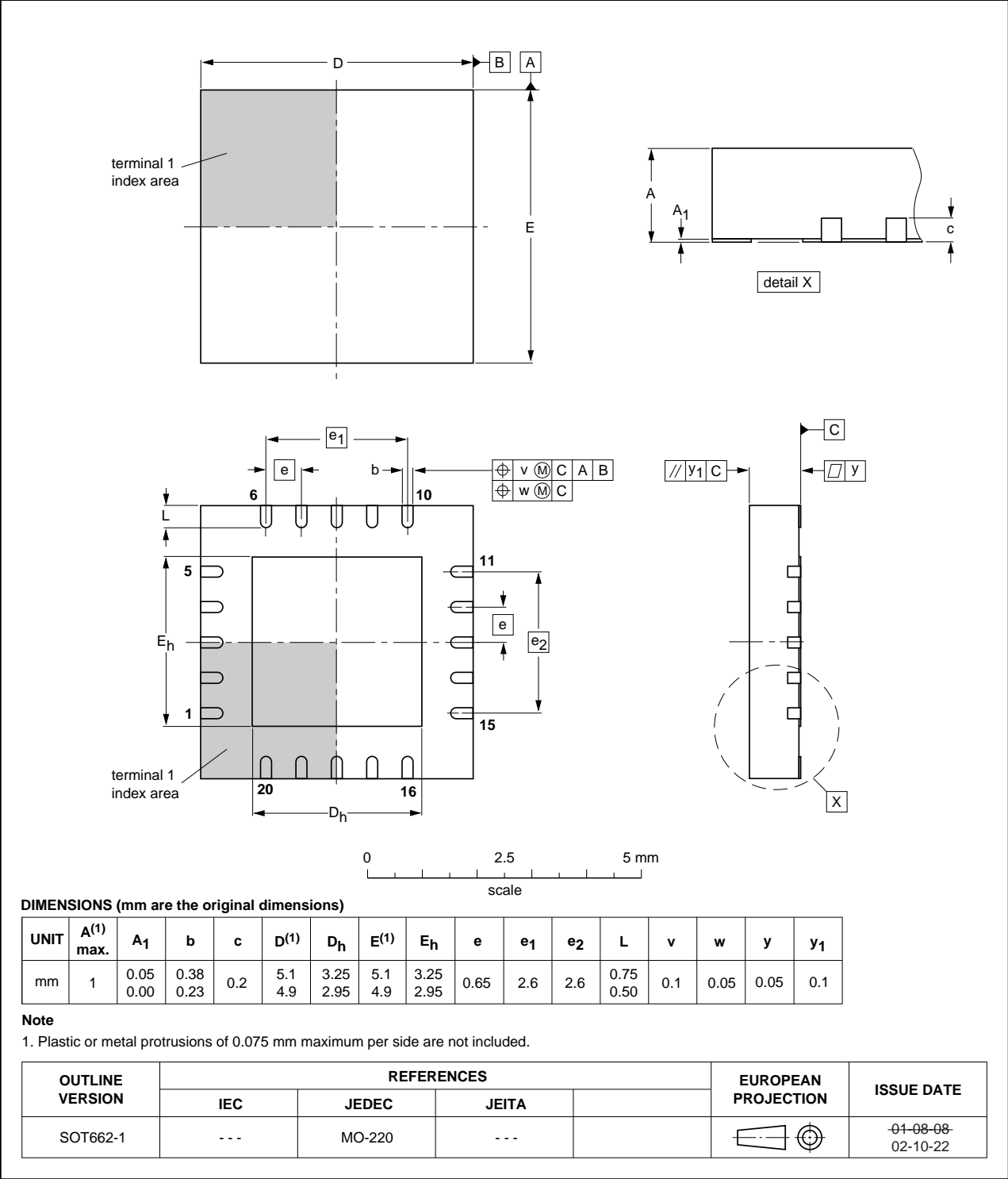


Fig 24. Package outline SOT662-1 (HVQFN20)

15. Soldering of SMD packages

This text provides a very brief insight into a complex technology. A more in-depth account of soldering ICs can be found in Application Note *AN10365 "Surface mount reflow soldering description"*.

15.1 Introduction to soldering

Soldering is one of the most common methods through which packages are attached to Printed Circuit Boards (PCBs), to form electrical circuits. The soldered joint provides both the mechanical and the electrical connection. There is no single soldering method that is ideal for all IC packages. Wave soldering is often preferred when through-hole and Surface Mount Devices (SMDs) are mixed on one printed wiring board; however, it is not suitable for fine pitch SMDs. Reflow soldering is ideal for the small pitches and high densities that come with increased miniaturization.

15.2 Wave and reflow soldering

Wave soldering is a joining technology in which the joints are made by solder coming from a standing wave of liquid solder. The wave soldering process is suitable for the following:

- Through-hole components
- Leadless or leaded SMDs, which are glued to the surface of the printed circuit board

Not all SMDs can be wave soldered. Packages with solder balls, and some leadless packages which have solder lands underneath the body, cannot be wave soldered. Also, leaded SMDs with leads having a pitch smaller than ~0.6 mm cannot be wave soldered, due to an increased probability of bridging.

The reflow soldering process involves applying solder paste to a board, followed by component placement and exposure to a temperature profile. Leaded packages, packages with solder balls, and leadless packages are all reflow solderable.

Key characteristics in both wave and reflow soldering are:

- Board specifications, including the board finish, solder masks and vias
- Package footprints, including solder thieves and orientation
- The moisture sensitivity level of the packages
- Package placement
- Inspection and repair
- Lead-free soldering versus SnPb soldering

15.3 Wave soldering

Key characteristics in wave soldering are:

- Process issues, such as application of adhesive and flux, clinching of leads, board transport, the solder wave parameters, and the time during which components are exposed to the wave
- Solder bath specifications, including temperature and impurities

15.4 Reflow soldering

Key characteristics in reflow soldering are:

- Lead-free versus SnPb soldering; note that a lead-free reflow process usually leads to higher minimum peak temperatures (see [Figure 25](#)) than a SnPb process, thus reducing the process window
- Solder paste printing issues including smearing, release, and adjusting the process window for a mix of large and small components on one board
- Reflow temperature profile; this profile includes preheat, reflow (in which the board is heated to the peak temperature) and cooling down. It is imperative that the peak temperature is high enough for the solder to make reliable solder joints (a solder paste characteristic). In addition, the peak temperature must be low enough that the packages and/or boards are not damaged. The peak temperature of the package depends on package thickness and volume and is classified in accordance with [Table 11](#) and [12](#)

Table 11. SnPb eutectic process (from J-STD-020D)

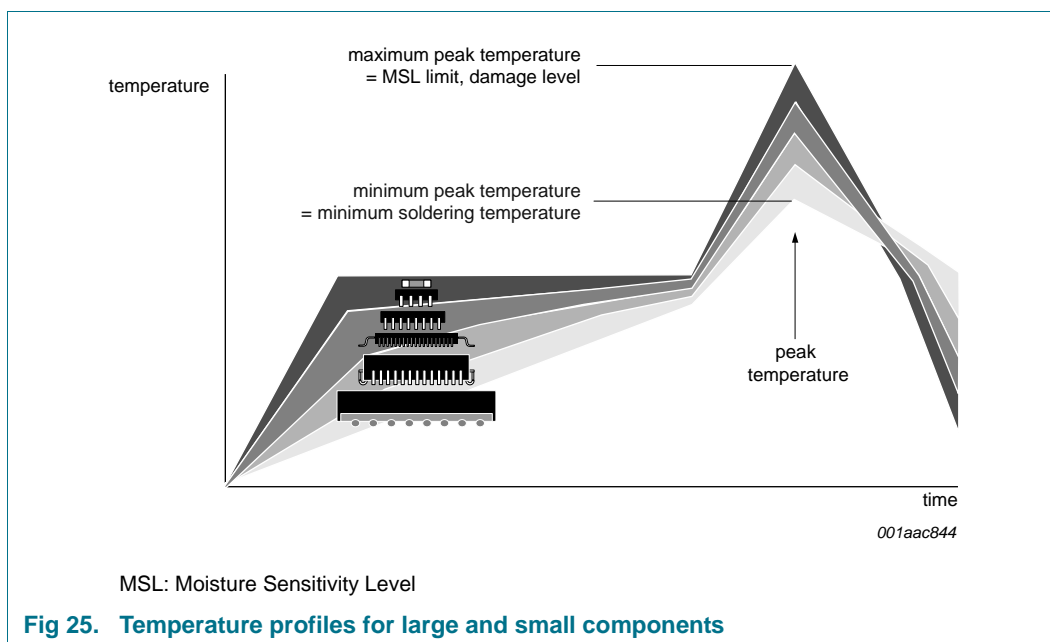
| Package thickness (mm) | Package reflow temperature (°C) | |
|------------------------|---------------------------------|-------|
| | Volume (mm ³) | |
| | < 350 | ≥ 350 |
| < 2.5 | 235 | 220 |
| ≥ 2.5 | 220 | 220 |

Table 12. Lead-free process (from J-STD-020D)

| Package thickness (mm) | Package reflow temperature (°C) | | |
|------------------------|---------------------------------|-------------|--------|
| | Volume (mm ³) | | |
| | < 350 | 350 to 2000 | > 2000 |
| < 1.6 | 260 | 260 | 260 |
| 1.6 to 2.5 | 260 | 250 | 245 |
| > 2.5 | 250 | 245 | 245 |

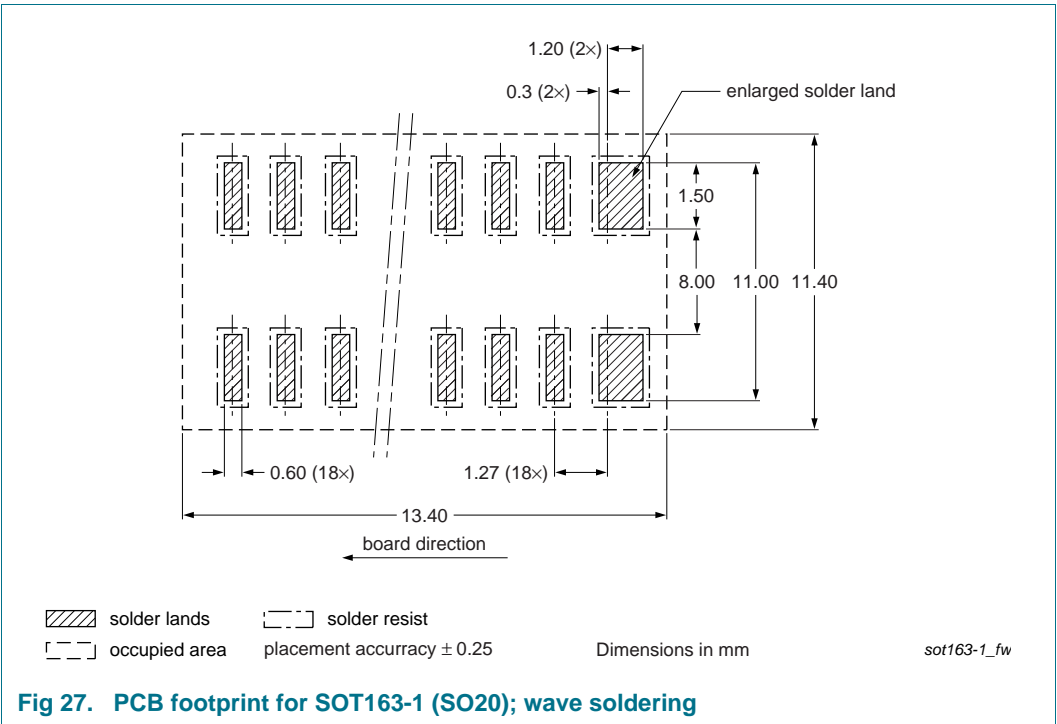
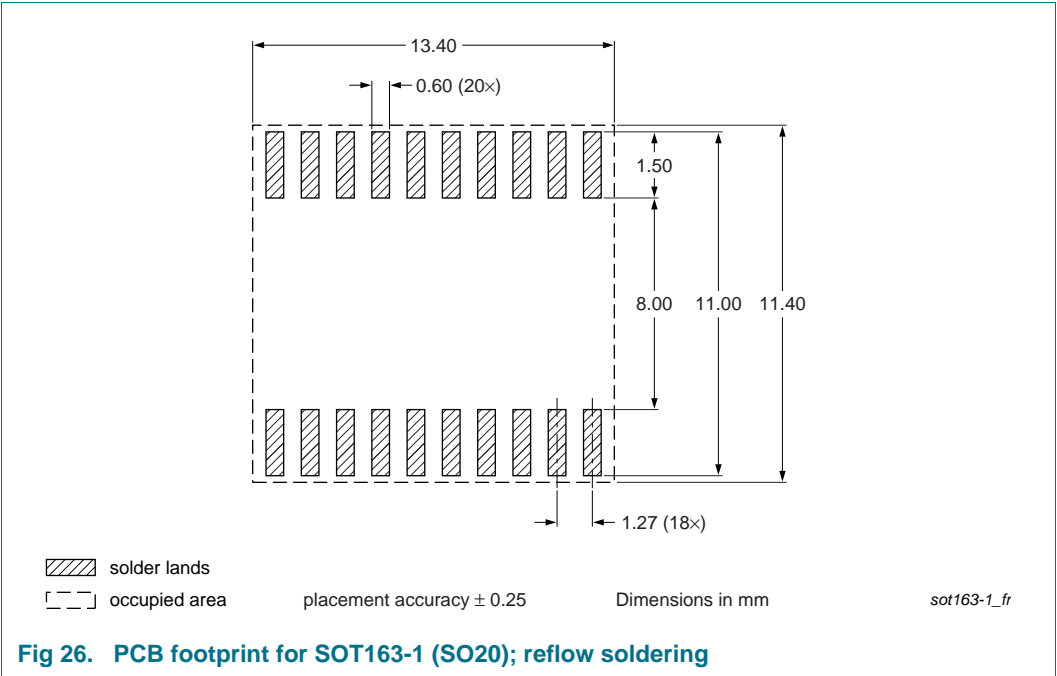
Moisture sensitivity precautions, as indicated on the packing, must be respected at all times.

Studies have shown that small packages reach higher temperatures during reflow soldering, see [Figure 25](#).



For further information on temperature profiles, refer to Application Note *AN10365* “Surface mount reflow soldering description”.

16. Soldering: PCB footprints



Footprint information for reflow soldering of TSSOP20 package

SOT360-1

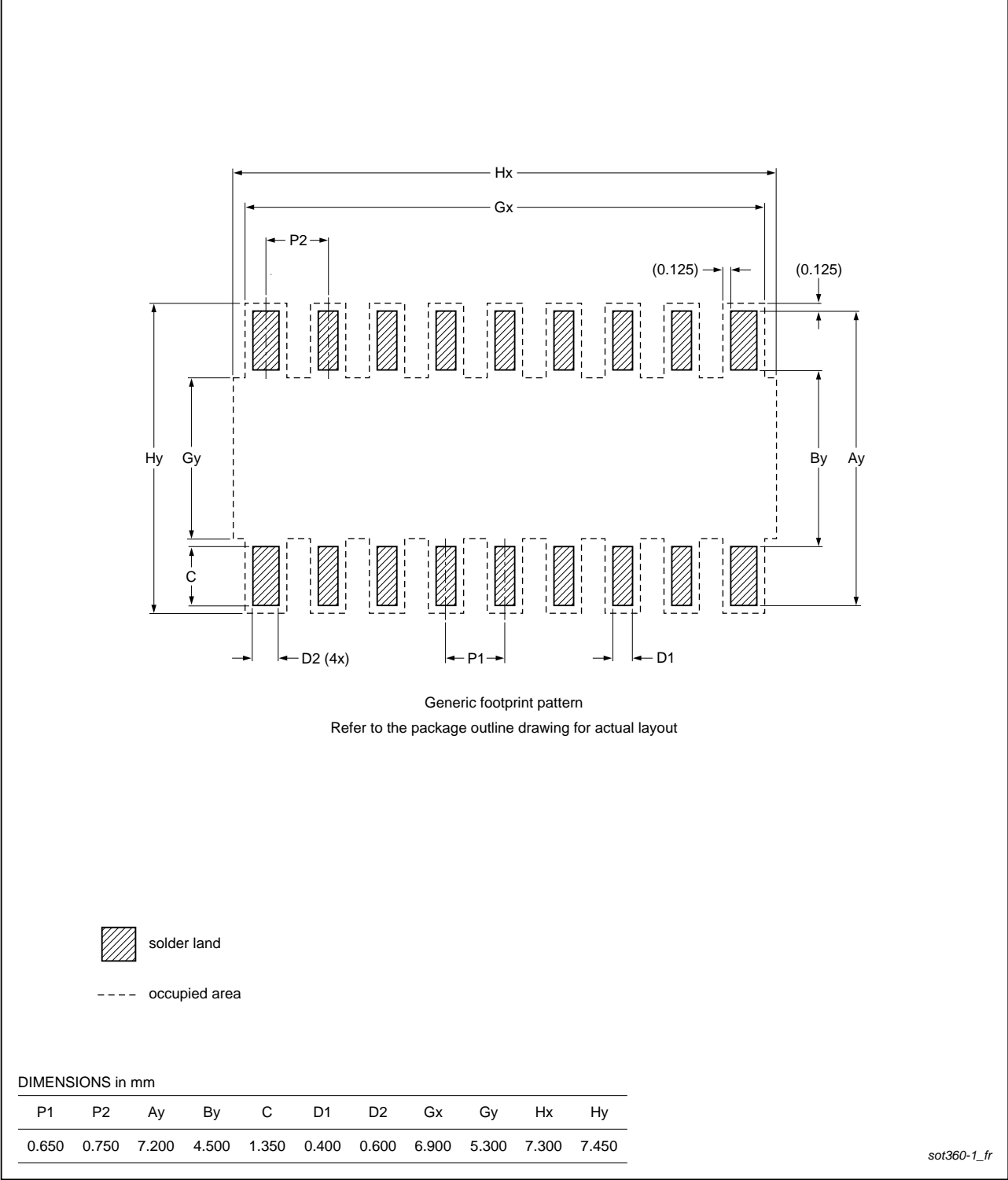


Fig 28. PCB footprint for SOT360-1 (TSSOP20); reflow soldering

Footprint information for reflow soldering of HVQFN20 package

SOT662-1

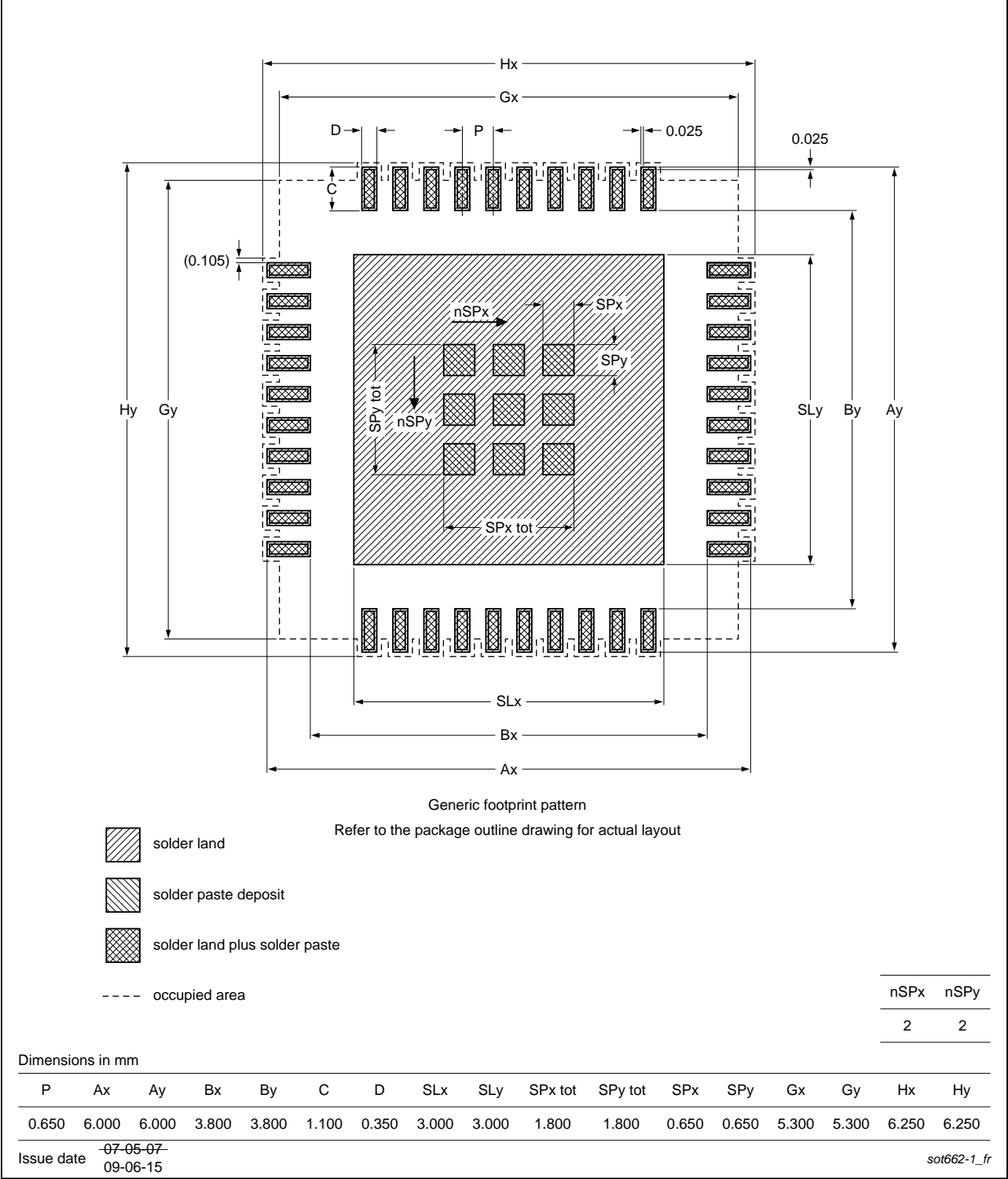


Fig 29. PCB footprint for SOT662-1 (HVQFN20); reflow soldering

17. Abbreviations

Table 13. Abbreviations

| Acronym | Description |
|----------------------|------------------------------|
| CDM | Charged-Device Model |
| DUT | Device Under Test |
| ESD | ElectroStatic Discharge |
| HBM | Human Body Model |
| IC | Integrated Circuit |
| I ² C-bus | Inter-Integrated Circuit bus |
| LSB | Least Significant Bit |
| MSB | Most Significant Bit |
| PCB | Printed-Circuit Board |
| POR | Power-On Reset |
| SMBus | System Management Bus |

18. Revision history

Table 14. Revision history

| Document ID | Release date | Data sheet status | Change notice | Supersedes |
|--|--------------|----------------------|---------------|----------------------|
| PCA9545A_45B_45C v.8 | 20130514 | Product data sheet | - | PCA9545A_45B_45C v.7 |
| Modifications: | | | | |
| <ul style="list-style-type: none"> • Section 2 “Features and benefits”, 18th bullet item: deleted phrase “200 V MM per JESD22-A115” • Table 1 “Ordering information”: added column “Topside marking” • Table 2 “Ordering options”: <ul style="list-style-type: none"> – deleted column “Topside mark” (moved to Table 1) – added columns “Orderable part number”, “Package”, “Packing method” and “Minimum order quantity” • Table 6 “Limiting values”: added $T_{j(max)}$ limits • Added Section 10 “Thermal characteristics” • Table 8 “Static characteristics at $V_{DD} = 2.3\text{ V to }3.6\text{ V}$”, sub-section “Select inputs A0, A1, INT0 to INT3, RESET”: Max value for V_{IH} corrected from “$V_{DD} + 0.5\text{ V}$” to “6 V” (documentation correction, no change to silicon) • Table 9 “Static characteristics at $V_{DD} = 4.5\text{ V to }5.5\text{ V}$”, sub-section “Select inputs A0, A1, INT0 to INT3, RESET”: Max value for V_{IH} corrected from “$V_{DD} + 0.5\text{ V}$” to “6 V” (documentation correction, no change to silicon) • Figure 17 “Definition of timing on the I²C-bus” modified: added $0.7 \times V_{DD}$ and $0.3 \times V_{DD}$ reference lines • Figure 19 “I²C-bus timing diagram” modified: added $0.7 \times V_{DD}$ and $0.3 \times V_{DD}$ reference lines • Added Section 16 “Soldering: PCB footprints” | | | | |
| PCA9545A_45B_45C v.7 | 20090619 | Product data sheet | - | PCA9545A_45B_45C v.6 |
| PCA9545A_45B_45C v.6 | 20070319 | Product data sheet | - | PCA9545A_45B_45C v.5 |
| PCA9545A_45B_45C v.5 | 20061017 | Product data sheet | - | PCA9545A v.4 |
| PCA9545A v.4 | 20060925 | Product data sheet | - | PCA9545A v.3 |
| PCA9545A v.3 | 20050303 | Product data sheet | - | PCA9545A v.2 |
| PCA9545A v.2 | 20040929 | Objective data sheet | - | PCA9545A v.1 |
| PCA9545A v.1 | 20040728 | Objective data sheet | - | - |

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| Document status ^{[1][2]} | Product status ^[3] | Definition |
|-----------------------------------|-------------------------------|---|
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[2] The term 'short data sheet' is explained in section "Definitions".

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